

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yoshiro Aoki</td> <td>03/08/2007</td> </tr> <tr> <td>Riyuusuke Kasamatsu</td> <td>03/08/2007</td> </tr> <tr> <td>Yukio Komatsu</td> <td>03/08/2007</td> </tr> </tbody> </table>		Name	Execution Date	Yoshiro Aoki	03/08/2007	Riyuusuke Kasamatsu	03/08/2007	Yukio Komatsu	03/08/2007
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Yoshiro Aoki	03/08/2007								
Riyuusuke Kasamatsu	03/08/2007								
Yukio Komatsu	03/08/2007								
RECEIVING PARTY DATA									
Name:	SUMCO CORPORATION								
Street Address:	2-1, Shibaura 1-chome								
City:	Minato-Ku, Tokyo								
State/Country:	JAPAN								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11695706</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11695706				
Property Type	Number								
Application Number:	11695706								
CORRESPONDENCE DATA									
Fax Number:	(212)521-5450								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	212-521-5403								
Email:	jegoldberg@reedsmith.com								
Correspondent Name:	Jules E. Goldberg, Reed Smith LLP								
Address Line 1:	599 Lexington Avenue, 29th Floor								
Address Line 4:	New York, NEW YORK 10022								
ATTORNEY DOCKET NUMBER:	JG-SU-5274/500577.20106								
NAME OF SUBMITTER:	Jules E. Goldberg								
Total Attachments: 3 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif									

CH \$40.00 11695706

**ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA**

Whereas, I/ We Yoshiro Aoki
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") has invented certain new and useful improvements in
Title: METHOD FOR MANUFACTURING SIMOX WAFER AND SIMOX WAFER OBTAINED BY THIS METHOD
which application for Letters Patent in the United States of America has been filed.

And Whereas, SUMCO CORPORATION of 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereinafter "Assignee") is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these presents does assign, transfer and set over unto the said Assignee for all the countries in the world, the full and exclusive right, title, and interest in and to the said invention, as fully set forth and described in the specification, and any patent issuing thereon

A. prepared and executed on
B. filed in the U.S. Patent and Trademark Office under Application No. 11/695,706
on 4/3/07 including any division, continuation, substitute or renewal application thereof; said invention, application and Letters Patent to be held and enjoyed by the said Assignee to the full end of the term for which said Letters Patent is granted, as fully and entirely as the same would have been held by the Assignor had this assignment and transfer not been made.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 3th day of March 2006

INVENTOR(S):

<u>Yoshiro Aoki</u>	<u>Yoshiro Aoki</u>	<u>1 08 / 03 / 2007</u>
Name	Signature	Date

WITNESS: _____ / _____
Signature Date

**ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA**

Whereas, I/ We Riyuusuke Kasamatsu
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") has invented certain new and useful improvements in
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Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 8th day of
March 2006

INVENTOR(S):

<u>Riyuusuke Kasamatsu</u>	<u>Ryusuke Kasamatsu</u>	<u>1 08 / 03 / 2007</u>
Name	Signature	Date

WITNESS: _____
Signature Date

**ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA**

Whereas, I/ We Yukio Komatsu
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") has invented certain new and useful improvements in
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In testimony whereof, the Assignor has hereunto set his hand this 8th day of
March 2006

INVENTOR(S):

<u>Yukio Komatsu</u>	<u>Yukio Komatsu</u>	<u>08/03/2007</u>
Name	Signature	Date

WITNESS: _____
Signature Date